

CLAIMS

1. – 17. (Canceled)

18. (Previously presented) An image sensor comprising:

a pixel section of the image sensor including routing lines, said pixel section having a first pitch, and

a decoder section of said image sensor including routing lines, said decoder section having a second pitch,

wherein the second pitch is smaller than the first pitch.

19. (Original) The image sensor of claim 18, wherein the decoder section comprises a plurality of generic blocks stitched together in a series, wherein adjacent generic blocks are separated by a stitching section including routing lines operative to connect signal lines in the adjacent generic blocks.

20. (Original) The image sensor of claim 18, further comprising a plurality of interconnect lines connected between the pixel section and the decoder section, wherein two or more of said interconnect lines are connected at an angle to accommodate the stitching sections.

21. (Previously presented) A method comprising:

patterning a pixel section of an image sensor including pixel features having a first pitch on a surface; and

patterning a decoder section of the image sensor including features having a second pitch which is smaller than the first pitch on the surface, wherein said features include routing lines.

22. (Original) The method of claim 21, wherein a ratio of the second pitch to the first pitch is less than approximately 0.98.

23. (Original) The method of claim 22, wherein the first pitch is approximately 9 μm and the second pitch is approximately 8.75 μm .

24. (Original) The method of claim 21, wherein a ratio of the second pitch to the first pitch is less than approximately 0.95.

25. (Original) The method of claim 24, wherein the first pitch is approximately 18 μm and the second pitch is approximately 17 μm .